

AMENDMENTS TO THE CLAIMS:

1. (Currently Amended) A mount structure for thermal fuse on circuit board, comprising:

a circuit board having a first surface where a predetermined circuit is formed; and
a second surface

a through opening provided in said circuit board; the through opening joining the first and second surfaces;

an electronic component attached to the first surface of said circuit board to extend across said through opening;

a thermal fuse provided on the second surface of said circuit board to enter said through opening, responding to temperature of said electronic component via a heat-conducting insulating member filling said through opening for breaking said predetermined circuit; and

a through hole provided in said circuit board, wherein said thermal fuse is electrically connected to said predetermined circuit via said through hole, wherein the through opening and the heat-conducting insulating member contained therein are free from electrical conductors in the space between the electronic component and the thermal fuse.

2. (Original) The mount structure for thermal fuse on circuit board according to claim 1, wherein

said heat-conducting insulating member is silicone resin.

Claim 3: (Cancelled)

4. (Original) The mount structure for thermal fuse on circuit board according to claim 1, wherein
said thermal fuse includes therein a rod-shaped fuse.